



## Material Composition

**Product**        **GS9074ACNE3**  
**Package**        **QFN 16L 4 x 4 x 0.9**  
**Manufacturer**   **Gennum Corporation**

**Date**        **12/03/2008**

Component	BOM Item	Weight Component mg	Substance	Weight of Substance mg	Homogeneous material	
					%	ppm
<b>Leadframe</b>	OLIN 194FH	17.79	Cu	17.35	97.51	975100
			Fe	0.42	2.36	23600
			Zn	0.02	0.13	1266
			P	0.00	0.00	34
			Sub-total	17.79	100.00	1000000
<b>Mold Compound</b>	Sumitomo EME G770HCD	22.86	Silica Fused	21.42	93.7	937000
			Epoxy Resin	0.69	3	30000
			Phenol Resin	0.69	3	30000
			Carbon Black	0.07	0.3	3000
			Sub-total	22.86	100.00	1000000
<b>Chip</b>		1.77	Si	1.76	99.40	994000
			Al	0.01	0.60	6000
			Sub-total	1.77	100.00	1000000
<b>Die Attach</b>	Sumitomo CRM 1076NS	1.10	Ag	0.88	80	800000
			EpoxyResin 1,2-Epoxy-3-(Tolyloxy)	0.12	10.5	105000
			Propane	0.07	6	60000
			Bisphenol-F	0.03	3	30000
			Dicyandiamide	0.01	0.5	5000
			Sub-total	1.10	100.00	1000000
<b>Wire</b>	GL2	0.42	Au	0.42	99.99	999900
<b>Terminals finish</b>		1.15	Sn	1.15	100.00	1000000
<b>Internal pad plating</b>		0.08	Ag	0.08	100.00	1000000
<b>Total</b>		45.16		45.16		

**GENNUM CORPORATION**

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